



Material Content Data Sheet



Sales Product Name		1EDI60I12AF		Issued		19. July 2018		
MA#		MA001281910						
Package		PG-DSO-8-51		Weight*		80.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.779	2.22	2.22	22159	22159
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		103	
	non noble metal	zinc	7440-66-6	0.033	0.04		411	
	non noble metal	iron	7439-89-6	0.660	0.82		8218	
wire	non noble metal	copper	7440-50-8	26.789	33.37	34.24	333675	342407
	noble metal	gold	7440-57-5	0.231	0.29	0.29	2878	2878
	encapsulation	organic material	carbon black	1333-86-4	0.148	0.18		1838
encapsulation	plastics	epoxy resin	-	4.770	5.94		59419	
	inorganic material	silicondioxide	60676-86-0	44.262	55.13	61.25	551308	612565
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10137	10137
plating	noble metal	silver	7440-22-4	0.095	0.12	0.12	1186	1186
glue	plastics	acrylic resin	-	0.153	0.19		1907	
	noble metal	silver	7440-22-4	0.543	0.68	0.87	6761	8668
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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